

Notice of References Cited	Application No. 09/762,881	Applicant(s) Narange et al
	Examiner M.L. Padgett	Group Art Unit 1762
		Page 1 of 1

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NON-PATENT DOCUMENTS

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X	Baum et al, "Photosensitive Circuitization of Dielectrics via Electroless Plating of metals", Metallized Plastics: Fundamentals and Applied Aspects, K.L. Mittal, ed., Plenum Press, New York, p. 9-17	1992 no month
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